

# MU10N160L

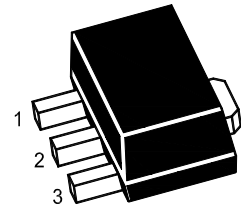
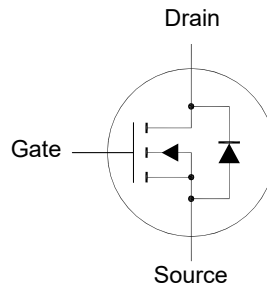
## N-Channel Enhancement Mode MOSFET

### Features

- Extremely low threshold voltage

### Applications

- Portable appliances
- Battery management
- High speed switch



1.Gate 2.Drain 3.Source  
SOT-89 Plastic Package

### Absolute Maximum Ratings (at $T_a = 25^\circ\text{C}$ unless otherwise specified)

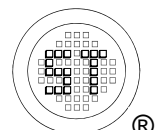
Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	100	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current	$I_D$	6 3	A
Peak Drain Current, Pulsed <sup>1)</sup>	$I_{DM}$	20	A
Total Power Dissipation <sup>2)</sup>	$P_{tot}$	2	W
Operating Junction and Storage Temperature Range	$T_j, T_{stg}$	- 55 to + 150	$^\circ\text{C}$

### Thermal Resistance Ratings

Parameter	Symbol	Max.	Unit
Thermal Resistance from Junction to Ambient <sup>2)</sup>	$R_{\theta JA}$	62.5	$^\circ\text{C}/\text{W}$
Thermal Resistance from Junction to Case	$R_{\theta JC}$	13	$^\circ\text{C}/\text{W}$

<sup>1)</sup> Pulse width  $\leq 10 \mu\text{s}$ , duty cycle  $\leq 1\%$ .

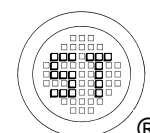
<sup>2)</sup> Device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper plate in still air.



# MU10N160L

## Characteristics at $T_a = 25^\circ\text{C}$ unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit
<b>STATIC PARAMETERS</b>					
Drain-Source Breakdown Voltage at $I_D = 250 \mu\text{A}$	$V_{(BR)DSS}$	100	-	-	V
Zero Gate Voltage Drain Current at $V_{DS} = 80 \text{ V}$	$I_{DSS}$	-	-	1	$\mu\text{A}$
Gate-Source Leakage at $V_{GS} = \pm 16 \text{ V}$	$I_{GSS}$	-	-	$\pm 100$	nA
Gate-Source Threshold Voltage at $V_{DS} = V_{DS}, I_D = 250 \mu\text{A}$	$V_{GS(th)}$	1.3	-	2.5	V
Drain-Source On-State Resistance at $V_{GS} = 10 \text{ V}, I_D = 6 \text{ A}$ at $V_{GS} = 4.5 \text{ V}, I_D = 4 \text{ A}$	$R_{DS(on)}$	- -	- -	150 160	m $\Omega$
<b>DYNAMIC PARAMETERS</b>					
Forward Transconductance at $V_{DS} = 5 \text{ V}, I_D = 4 \text{ A}$	$g_{Fs}$	-	9.8	-	S
Gate Resistance at $V_{DS} = 0 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	$R_g$	-	1.1	-	$\Omega$
Input Capacitance at $V_{DS} = 50 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	$C_{iss}$	-	1155	-	pF
Output Capacitance at $V_{DS} = 50 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	$C_{oss}$	-	28	-	pF
Reverse Transfer Capacitance at $V_{DS} = 50 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	$C_{rss}$	-	25	-	pF
Gate Charge Total at $V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 4 \text{ A}$ at $V_{DS} = 50 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 4 \text{ A}$	$Q_g$	- -	20 9	- -	nC
Gate to Source Charge at $V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 4 \text{ A}$	$Q_{gs}$	-	4	-	nC
Gate to Drain Charge at $V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 4 \text{ A}$	$Q_{gd}$	-	2.4	-	nC
Turn-On Delay Time at $V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 4 \text{ A}, R_g = 3.3 \Omega$	$t_{d(on)}$	-	14	-	ns
Turn-On Rise Time at $V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 4 \text{ A}, R_g = 3.3 \Omega$	$t_r$	-	4	-	ns
Turn-Off Delay Time at $V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 4 \text{ A}, R_g = 3.3 \Omega$	$t_{d(off)}$	-	13	-	ns
Turn-Off Fall Time at $V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 4 \text{ A}, R_g = 3.3 \Omega$	$t_f$	-	2	-	ns
<b>Body-Diode PARAMETERS</b>					
Drain-Source Diode Forward Voltage at $V_{GS} = 0 \text{ V}, I_S = 1 \text{ A}$	$V_{SD}$	-	-	1.3	V
Body-Diode Continuous Current	$I_S$	-	-	3	A
Body Diode Reverse Recovery Time at $I_S = 4 \text{ A}, di/dt = 100 \text{ A} / \mu\text{s}$	$t_{rr}$	-	21	-	ns
Body Diode Reverse Recovery Charge at $I_S = 4 \text{ A}, di/dt = 100 \text{ A} / \mu\text{s}$	$Q_{rr}$	-	22	-	nC



## Electrical Characteristics Curves

Fig. 1 Typical Output Characteristics

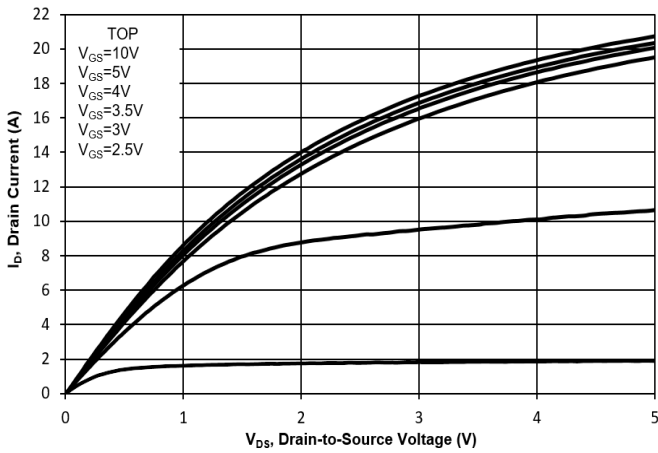


Fig. 2 Typical Transfer Characteristics

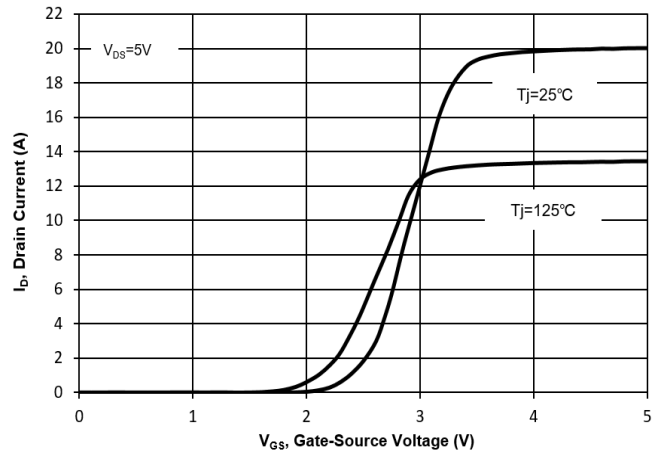


Fig. 3 On-Resistance vs. Drain Current

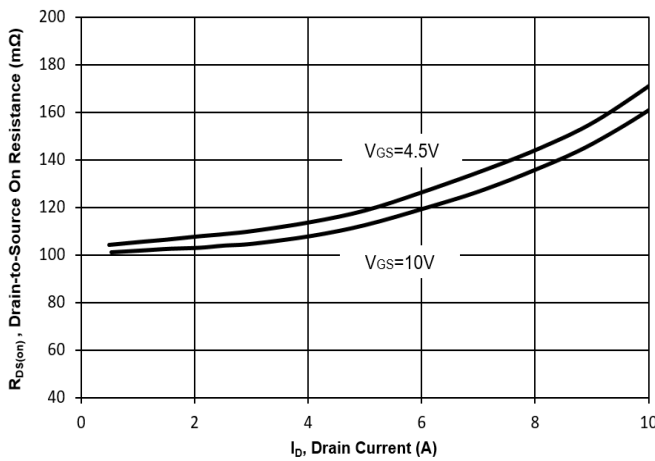


Fig. 4 On-Resistance vs. Gate-Source Voltage

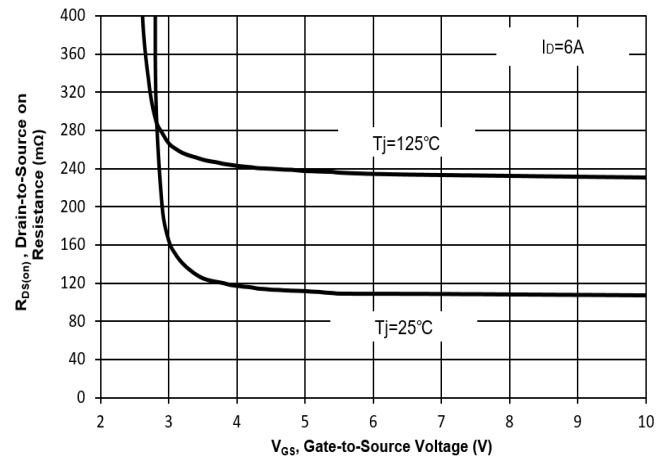


Fig. 5 On-Resistance vs.  $T_j$

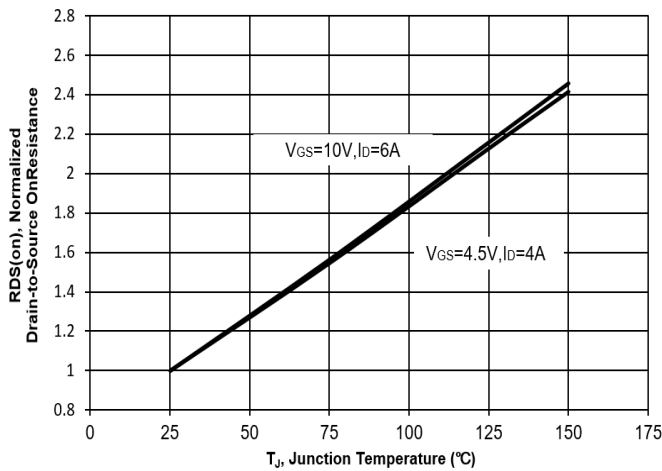
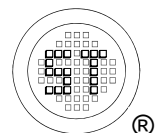
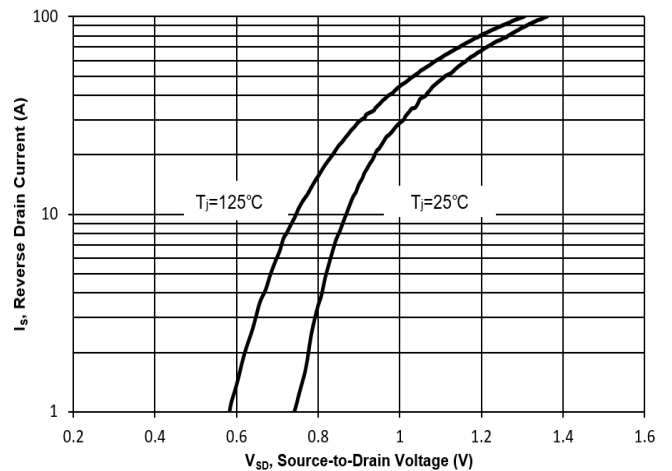


Fig. 6 Typical Body-Diode Forward Characteristics



## Electrical Characteristics Curves

Fig. 7 Typical Junction Capacitance

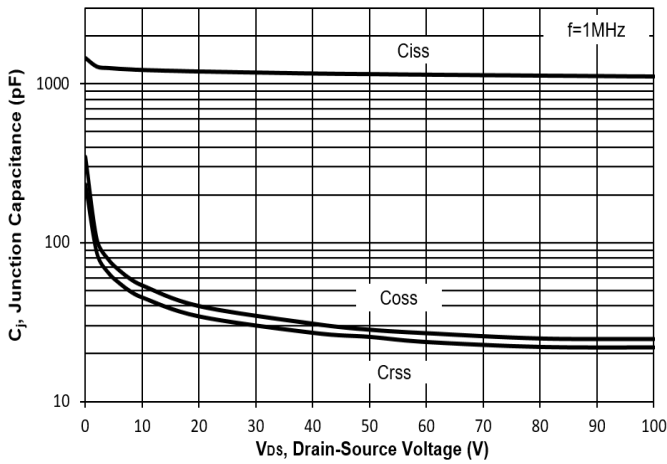


Fig. 8 Drain-Source Leakage Current vs.  $T_j$

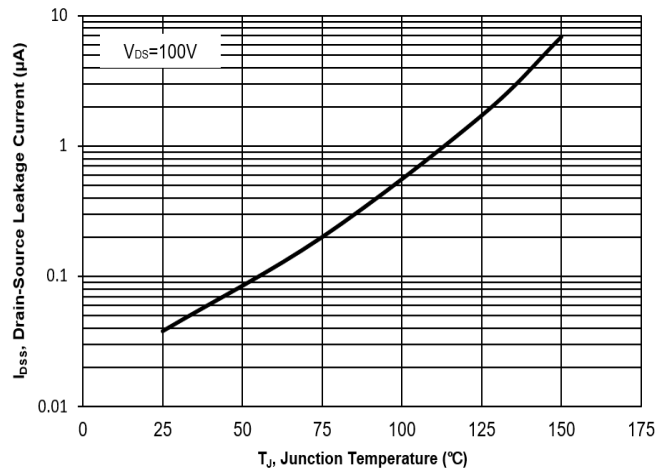


Fig. 9  $V_{(BR)DSS}$  vs. Junction Temperature

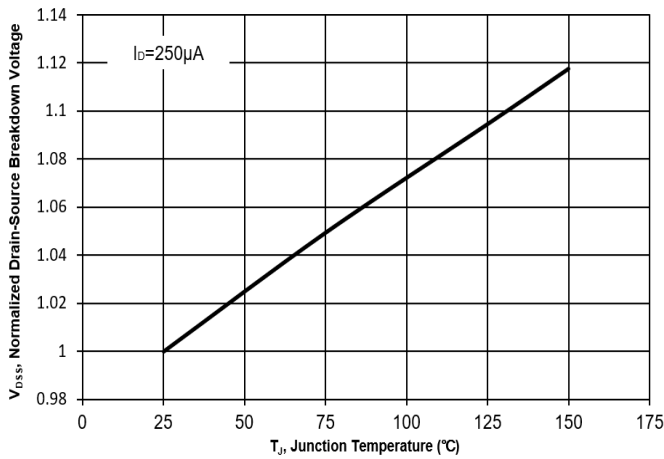


Fig. 10 Gate Threshold Variation vs.  $T_j$

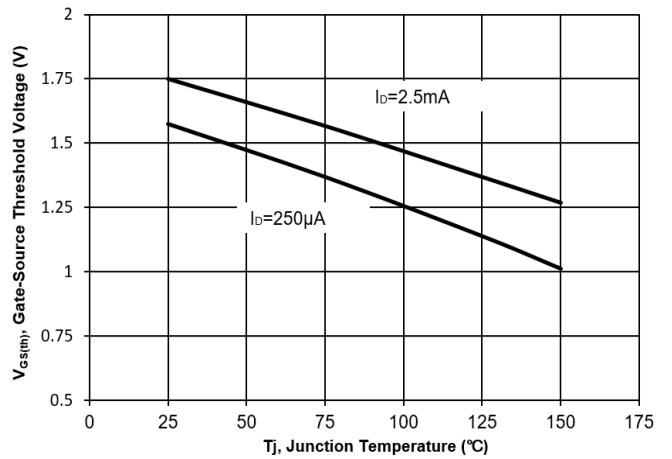
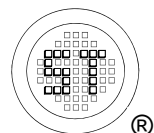
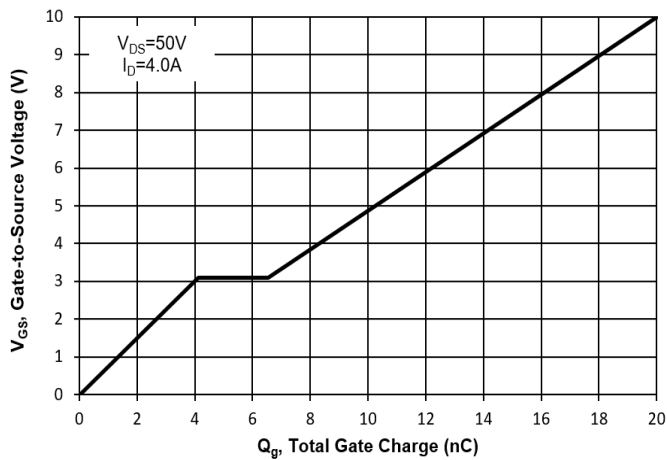


Fig. 11 Gate Charge



## Test Circuits

Fig.1-1 Switching times test circuit

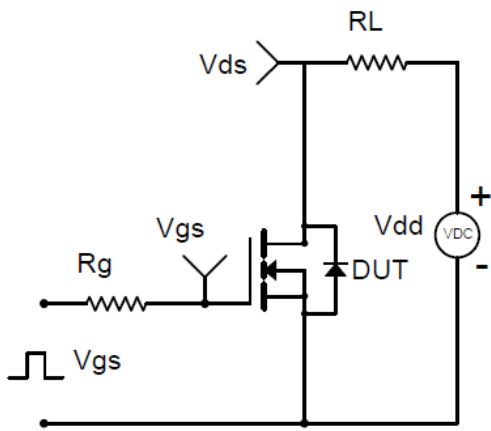


Fig.1-2 Switching Waveform

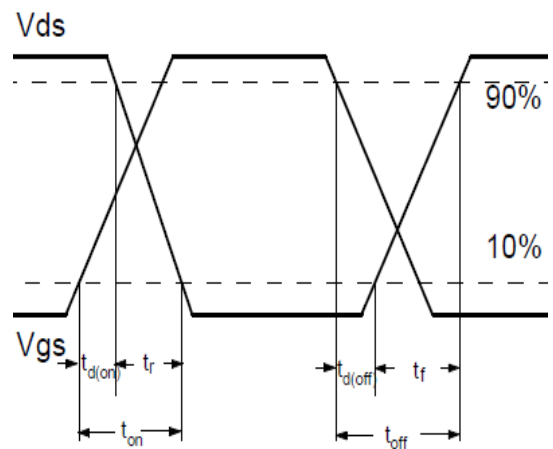


Fig.2-1 Gate charge test circuit

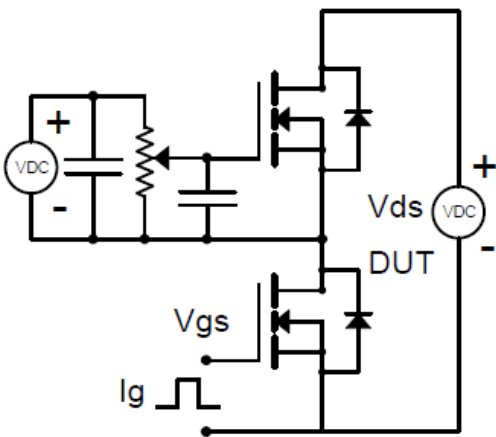
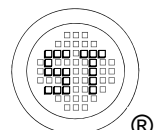
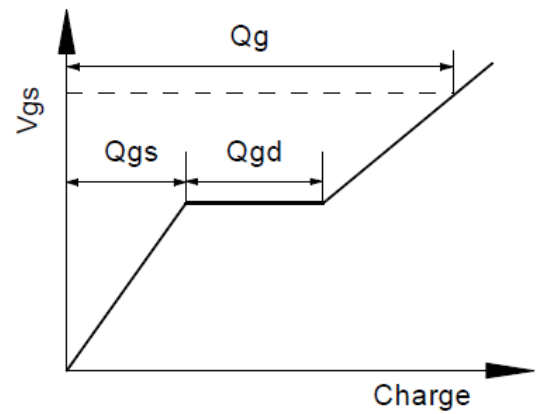


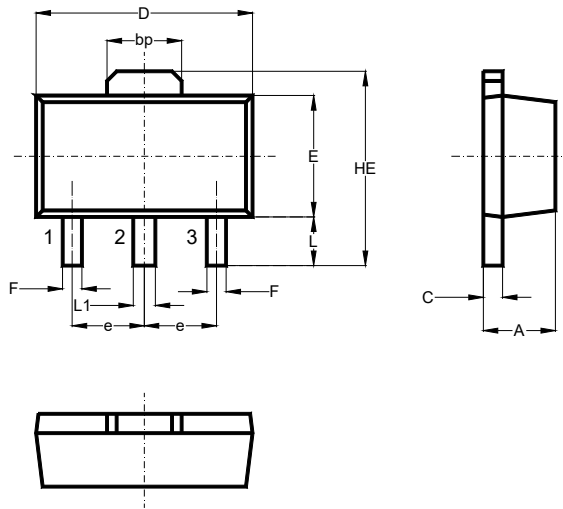
Fig.2-2 Gate charge waveform



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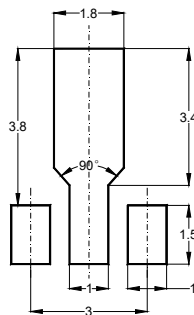
## Package Outline (Dimensions in mm)

SOT-89



Unit	A	bp	C	D	E	F	HE	e	L	L1
mm	1.6	1.60	0.5	4.6	2.6	0.45	4.25	1.5	1.05	0.51
	1.4	1.50	0.3	4.4	2.4	0.35	3.75	typ.	0.95	0.41

## Recommended Soldering Footprint



## Packing information

Package	Tape Width (mm)	Pitch		Reel Size		Per Reel Packing Quantity
		mm	inch	mm	inch	
SOT-89	12	8 ± 0.1	0.315 ± 0.004	178	7	1,000
				330	13	4,000

## Marking information

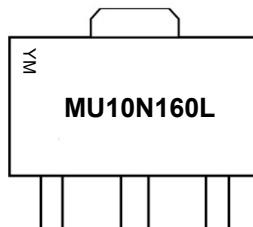
" MU10N160L " = Part No.

" YM " = Date Code Marking

" Y " = Year

" M " = Month

Font type: Arial



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